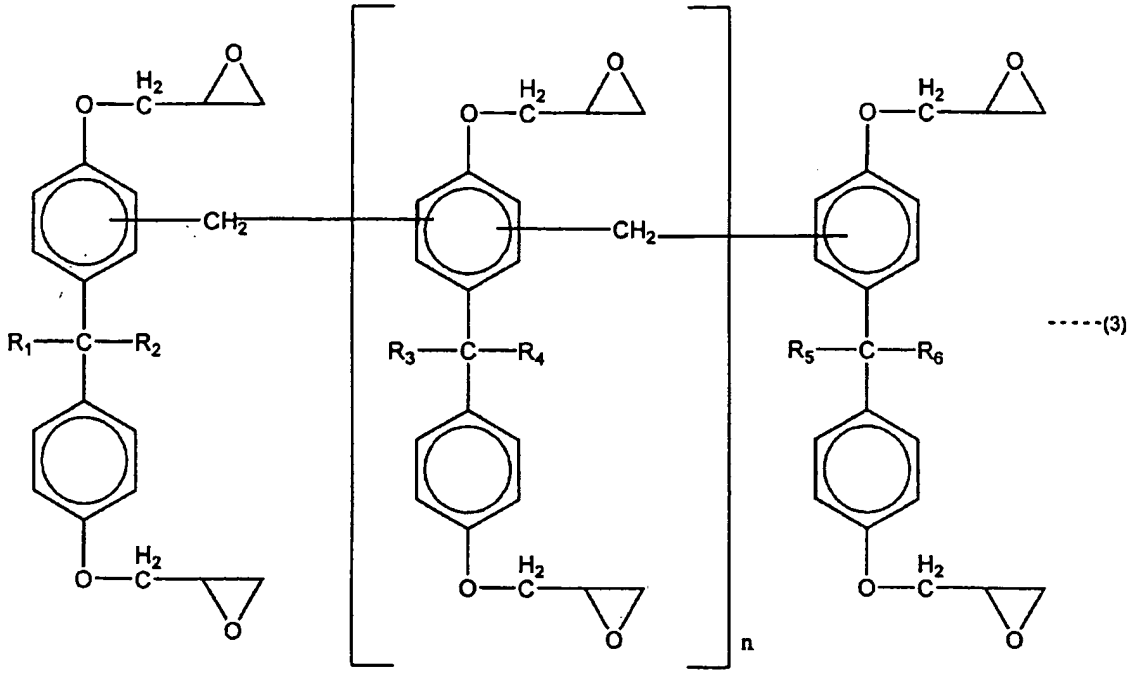
AMENDMENTS TO THE CLAIMS

1 to 8. (Canceled)

9. (Currently Amended) A photosensitive resin composition comprising:

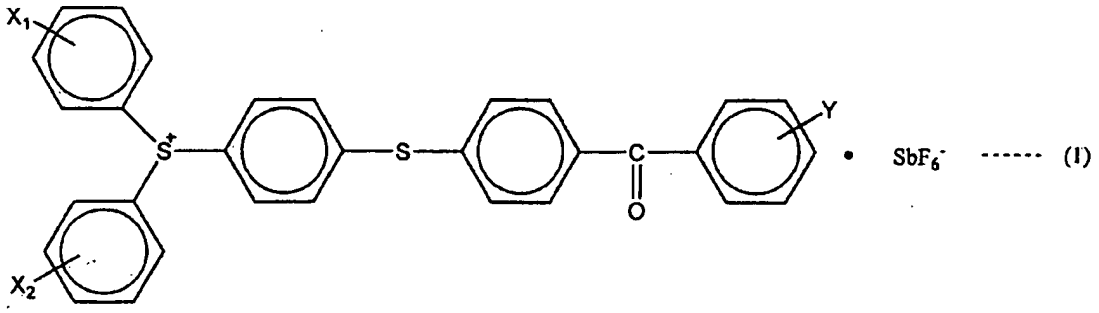
a multi-functional bisphenol A novolac epoxy resin, a functionality of which is 5-functional groups or more and represented by general formula (3) shown below:



-----(3)

~~(in the formula,~~wherein R_1 to R_6 are independently H or CH_3, respectively, n indicates zero or larger ~~integer);~~ integer and

a cation polymerization initiator represented by general formula (1) shown below:

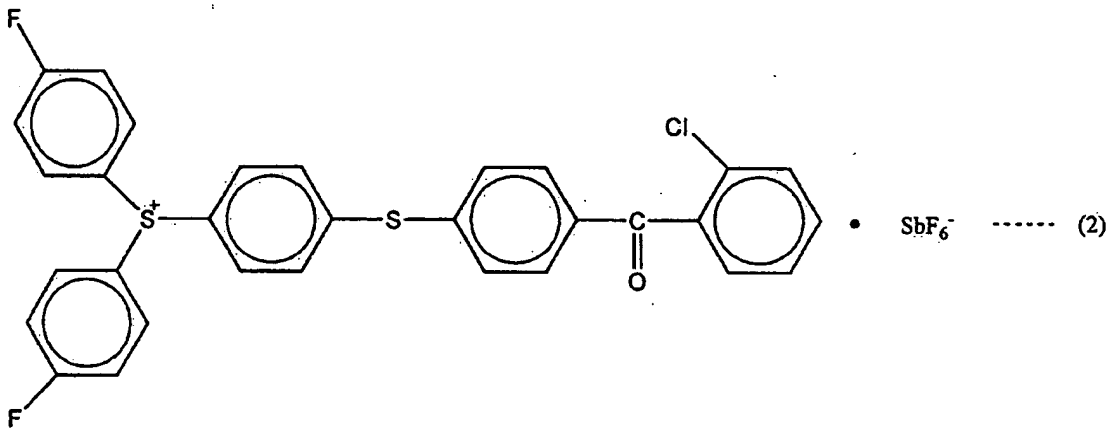


$\bullet\ SbF_6^-$ ------ (1)

~~(in the formula,~~wherein X_1 and X_2 indicate a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to

which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond, respectively, and they may be identical to or different from one another, and Y indicates a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond[[)]], said composition further comprising a naphthol sensitizer.

10. (Previously Presented) The photosensitive resin composition according to claim 9, wherein the cation polymerization initiator is a compound represented by chemical formula (2) shown below:



11. (Previously Presented) The photosensitive resin composition according to claim 9, further comprising a linear polymeric 2-functional epoxy resin.

12. (Cancelled)

13. (Previously Presented) The photosensitive resin composition according to claim 9, further comprising γ-butyrolactone.

14. (Previously Presented) A photosensitive resin composition laminate comprising:

a photosensitive resin composition layer obtained from the photosensitive resin

composition according to clam 9; and

a protective film,

wherein at least one side of the photosensitive resin composition layer is protected with the protective film.

15. (Previously Presented) A method of forming a pattern comprising the steps of:

applying the photosensitive resin composition according to claim 9 on a desired base and then drying the photosensitive resin composition;

exposing a radiation beam on a photosensitive resin composition layer to form given resin patterns;

developing the beam-exposed photosensitive resin composition layer; and

heat-treating the resulting resin patterns to yield cured resin patterns of given shapes.

16. (Previously Presented) A method of forming a pattern comprising the steps of:

peeling the protective film away from the photosensitive resin composition laminate according to claim 14;

attaching a resulting photosensitive resin composition layer on a desired base;

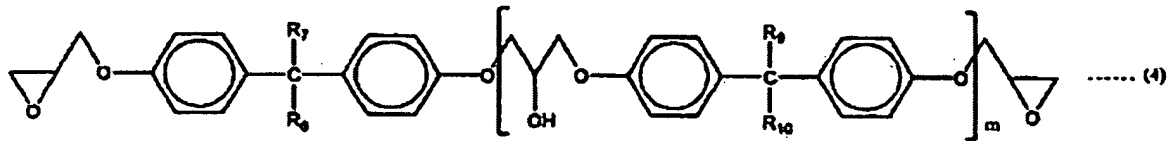
exposing a radiation beam on the photosensitive resin composition layer to form a given pattern;

developing the beam-exposed photosensitive resin composition layer; and

heat-treating the resulting resin patterns to yield cured resin patterns of given shapes.

17. (Previously Presented) The photosensitive resin composition according to claim 9, wherein a content of the multi-functional bisphenol A novolac epoxy resin, a functionality of which is 5-functional groups or more is 80 to 99.9 mass% based on a solid content of the photosensitive resin composition.

18. (New) The photosensitive resin composition according to claim 11, wherein the linear polymeric 2-functional epoxy resin is a compound represented by general formula (4) shown below:



..... (4)

wherein R_7 to R_{10} are H or CH_3, respectively. "m" is 0 (zero) or larger integer, which expresses the number of repeating units.